

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	1	("6306680").PN.	USPAT; USOCR	OR	OFF	2005/10/14 21:17
L2	1082	(@ad<"20000428") and (wafer adj (scale or processing)) and (ball or balls or solder)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/14 22:52
L4	367	L2 and (encapsulant or encpasulate or epoxy)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/14 21:22
L5	1	("6908784").PN.	USPAT; USOCR	OR	OFF	2005/10/14 21:25
L6	0	("L4and(cutorcuttingorsaworsawing ordicing)").PN.	USPAT; USOCR	OR	OFF	2005/10/14 21:25
L7	269	L4 and (cut or cutting or saw or sawing or dicing)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/14 21:30
L8	3694	(wafer same (encapsulate or epoxy or encapsulant)) and (cut or cutting or saw or sawing or dicing)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/14 22:52
L9	378	L8 and (@ad<"20000428") and (CMP or polish or polishing or grind or grinding)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/14 21:46
L10	346	L9 not L7	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/14 21:32
L11	1064	(wafer with (grind or grinding)) and (cut or cutting or saw or sawing or dicing) and (ball or balls or solder or bump or bumps)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/14 21:46

L12	1458	(wafer with (grind or grinding or cmp or polish)) and (cut or cutting or saw or sawing or dicing) and (ball or balls or solder or bump or bumps)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/14 21:46
L13	2316	(wafer with (grind or grinding or cmp or polish\$3)) and (cut or cutting or saw or sawing or dicing) and (ball or balls or solder or bump or bumps)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/14 21:46
L14	698	L13 and (@ad<"20000428")	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/14 21:47
L15	615	L14 not L10	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/14 21:47
L16	590	L14 not L9	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/14 22:03
L17	8	(("5798285") or ("5801073") or ("5841193") or ("5854085") or ("5915170") or ("6114753") or ("6166436") or ("6194290")).PN.	USPAT; USOCR	OR	OFF	2005/10/14 22:03
L18	905	(@ad<"20000428") and ("csp" or (chip near scale)) and (encapsulate or epoxy or encapsulant or polymer) and (ball or balls or bump or bumps)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/14 22:10
L19	893	L18 not L16	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/14 22:10
L20	775	l8 and (wafer with (tape or polyimide))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/14 22:52

L21	117	L20 and (@ad<"20000428") and (ball or balls or solder)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/14 22:53
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